

## Product features

High precision machining technology

Low temperature drift, high power.

Ceramic substrate, 50  $\Omega$  coplanar waveguide

Gold wire bonding

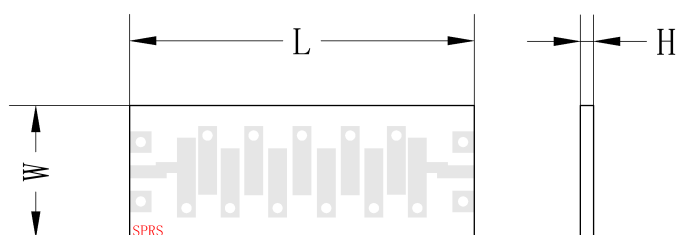
## Tech specifications

| Items              | Parameters      | Units |
|--------------------|-----------------|-------|
| Center Frequency   | 18.3            | GHz   |
| Bandwidth          | 16.0-20.6       | GHz   |
| Center loss        | 2.1             | dB    |
| Ripple             | 1.0             | dB    |
| VSWR               | 1.7:1           |       |
| Group delay ripple | 0.5             | ns    |
| Rejection          | 40@DC-14.1GHz   | dBc   |
| Rejection          | 40@22.9-40.0GHz | dBc   |

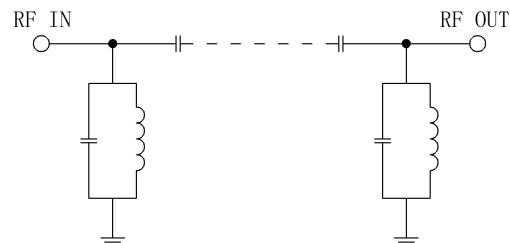
## Other requirement (Design assurance)

|               |                      |
|---------------|----------------------|
| power         | 2W CW                |
| Work Temp.    | -55~+85°C            |
| Storage Temp. | -55~+125°C           |
| Outline size  | L:7.5, W:3.0, h:0.26 |

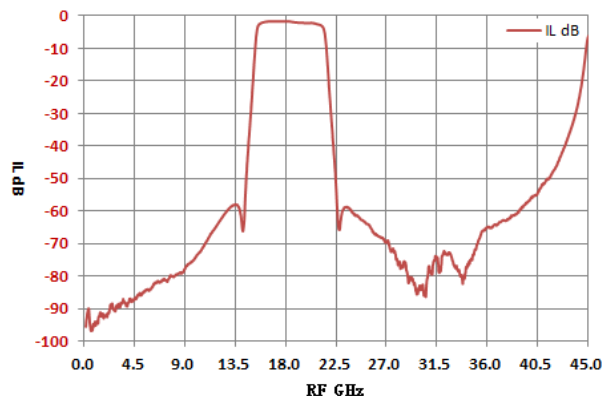
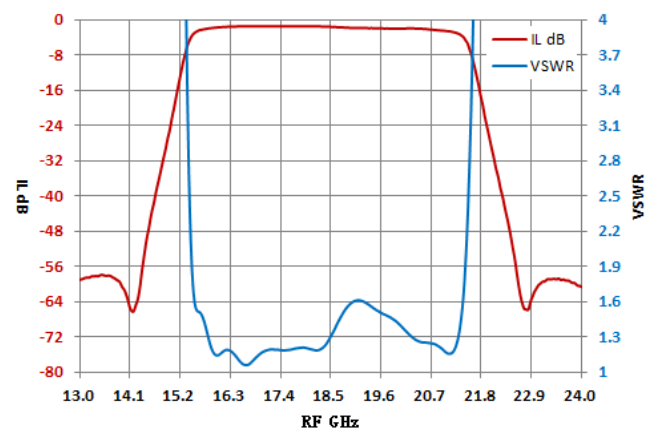
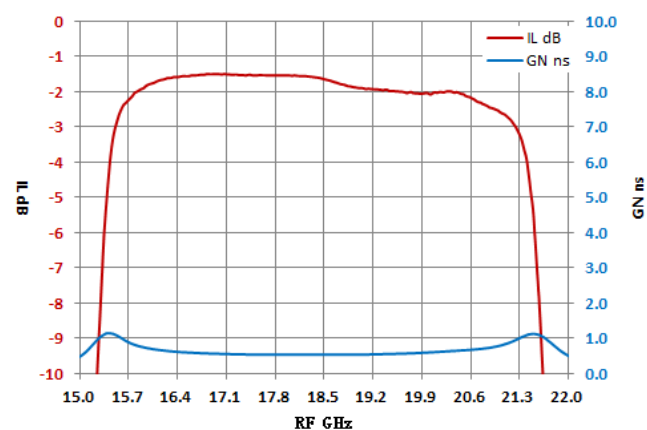
## Outline drawing: Port centered



## Schematic diagram

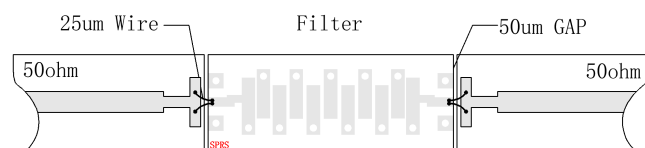


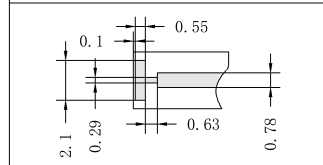
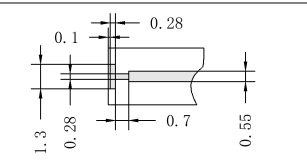
## Typical test curve



Note: The specifications and performance data contained in this data sheet are based on tests established by CMW.

## Suggested PCB Layout



| PCB Rogers5880, h: 0.254mm                                                                                                            | PCB Rogers4350B, h: 0.254mm                                                                                                          |
|---------------------------------------------------------------------------------------------------------------------------------------|--------------------------------------------------------------------------------------------------------------------------------------|
|  <p>Dimensions: 0.1, 0.55, 0.29, 0.63, 0.78, 2.1</p> |  <p>Dimensions: 0.1, 0.28, 0.7, 0.55, 1.3, 0.28</p> |

## Note

- 1: 0.1mm from the side wall, 2.75mm from the surface to the upper cover.
- 2: Suggest using conductive adhesive for bonding;
- 3: The chip should be installed on kovar alloy or molybdenum copper;
- 4: Suggest using a T-shaped structure for microstrip bonding.